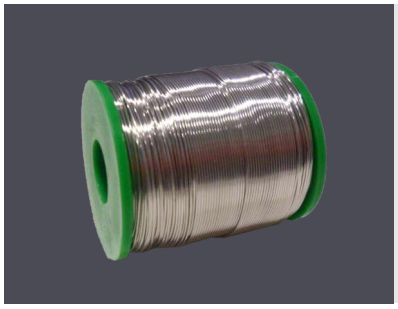
AUTOMOTIVE RANGE

Solder Wire - Lead Free



Product Description

- Sn99.3Cu0.7 RoHS Compliance Solder Wires are being formulated with High Virgin Raw Metals Processed in state-of-the-art Vaccualloy Technology that brings world class Quality along. Here, Oxygen interaction with Alloy is Nil and thus, Dross formulation is reduced at PCB Assembly Process. Also an increase flow rate & reduced impurities found. Sn99.3Cu0.7 Alloy is compatible for a typical range of Flux Application Formulas used in Electronics Industry Today.
- Soldering Wires conforms to RoHS, JIS, ANSI, IPC, DIN, ISO standards.

Item No.	Description	Weight (g)
SOL14	Solder Wire - Lead Free 22 SWG / 0.71 mm	500
SOL15	Solder Wire - Lead Free 18 SWG / 1.22 mm	500
SOL16	Solder Wire - Lead Free 16 SWG / 1.63 mm	500
SOL17	Solder Wire - Lead Free 10 SWG / 3.25 mm	500

Technical Details:

Storage And Handling

- Do not use Fire near storage area.
- Store in Dry, Cool and Non-Corrosive environment.
- Wear Personal Protective Equipments while Handling.
- Wear Personal Protective Equipments while Processing.

Product Specification

No.	Item	Specification	Standard
1	Appearance	Bright and shiny surface finishes	
2	Alloy	Sn99.3/Cu0.7	JIS-Z-3282 A CLASS
3	Melting Point	227^{0}C	DSC
4	Flux Content	2.0 ±0.5 %	JIS-Z-3283
5	Halide Content Under	0.1%	JIS-Z-3283
6	Gravity	7.4gm/cm^3 at 20^{0}C	
7	Spread ability	> 80%	JIS-Z-3197
8	Packaging	500gm	
9	Diameters/ Tolerances	Up to 0.30mm ± 0.02 mm	JIS-Z-3283
10	Flux Type	ROL0	J-STD-004
11	RoHS Complaint	Yes	International Standards
12	Features	Excellent solder joint reliability. Superior joint strength. Excellent thermal & Mechanical fatigue resistance. Low cleaning required after solder joint.	
13	Purpose	For use in applications requiring good activation.	

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Physical Properties

No.	Test Item	Test Result	Test Method
1	Silver Chromate Test	PASS	IPC-TM-650, 2.6.33
2	Copper Mirror Test	PASS	IPC-TM-650, 2.6.32
3	Copper plate Corrosion	PASS	JIS-Z-3197, 6.6.1
4	S.I.R Test	$1x10^{9}$up	IPC-TM-650, 2.6.3.3
5	Electro migration Test	$1x10^{112}$up	IPC-TM-650, 2.6.14.1

Alloy Composition

(Sn)	(Cu)	(Zn)	(Al)	(Sb)	(Fe)	(Fe)	(As)	(Bi)	(Cd)	(Pb)
REM	0.3 - 0.7	0.002 MAX	0.002 MAX	0.12 MAX	0.02 MAX	0.02 MAX	0.03 MAX	0.10 MAX	0.002 MAX	0.02 MAX